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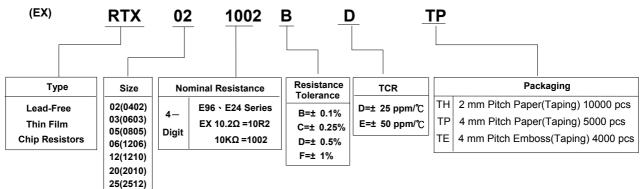
Thin Film Chip Resistors Product Specification

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1 Scope:

This specification is applicable to lead and halogen free RTX series thin film chip resistors.

2 Explanation Of Part Numbers:



3 General Specifications:

	Rated	Max.	Max.	T.C.R.	Resistance Range			
Туре	Power at 70℃	Working Voltage	Overload Voltage	(ppm/°C)	B(± 0.1%) E-96 ∖ E24	C(± 0.25%) E-96		F(<u>+</u> 1%) E-96
RTX02	$\frac{1}{16}$ W	50V	100V	± 25		10 Ω~	121K ()	
	16			± 50		10 11		
RTX03	<u>1</u> _w	75V	150V	± 25		10 Ω ~	681K ()	
	$\frac{1}{10}$ W	100	1007	± 50		10 22	0011(32	
DTYOE	1 w	1501/	2001/	± 25		100	1 5140	
RTX05	$\frac{1}{8}$ W	150V	300V	± 50	10 Ω ~ 1.5MΩ			
RTX06	_1_w	200V	400V	± 25	- 10Ω ~ 1.5MΩ			
RTA00	$\frac{1}{8}$ W	2000	400 v	± 50				
RTX12	$\frac{1}{4}$ W	200V	400V	± 25				
KIAI2	4	2000	400 v	± 50		10 22	111122	
RTX20	_1_w	200V	400V	± 25		100 -	- 1 M O	
RIA20	$\frac{1}{2}$ W	200 v	400 V	± 50	10 Ω ~ 1ΜΩ			
RTX25	$\frac{3}{4}$ W	200V	400V	± 25				
R1A23	<u>4</u> w	200 v	400 v	± 50				
Ope	rating Temp	perature Ran	ge		-	–55℃ ~ +125	5°C	

Approved

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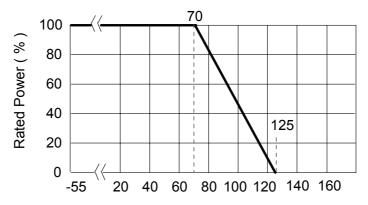
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3.1 Power Derating Curve:

Operating Temperature Range : $-55^{\circ}C \sim 125^{\circ}C$

For resistors operated in ambient temperatures above 70 $^\circ\!C$, power rating shall be derated in accordance with figure below.



3.2 Voltage Rating:

Rated Voltage: The resistor shall have a DC continuous working voltage or a rms. AC continuous working voltage at commercial-line frequency and wave form corresponding to the power rating, as determined from the following:

 $E = \sqrt{R \times P}$

E= Rated voltage (v) P= Power rating (w) R= Nominal resistance(Ω)

4 Dimensions:

Dir	Dimensions		w	н	L1	L2
TYPE	Size Code					
RTX02	0402	1.00± 0.10	0.50± 0.05	0.30± 0.05	0.20± 0.10	0.25± 0.10
RTX03	0603	1.60± 0.10	0.80± 0.10	0.45± 0.10	0.30± 0.15	0.30± 0.15
RTX05	0805	2.00± 0.10	1.25± 0.10	0.50± 0.10	0.35± 0.20	0.35± 0.15
RTX06	1206	3.05± 0.10	1.55± 0.10	0.55 ^{+0.10} -0.05	0.45± 0.20	0.35± 0.15
RTX12	1210	3.05± 0.10	2.55± 0.10	0.55± 0.10	0.50± 0.20	0.50± 0.20
RTX20	2010	5.00± 0.20	2.50± 0.20	0.55± 0.10	0.60± 0.20	0.60± 0.20
RTX25	2512	6.30± 0.20	3.20± 0.20	0.55± 0.10	0.60± 0.20	0.60± 0.20

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RALE 旺言	1 1 1 1 1 1	Film Chip Speci	Resistors	s Product	Document No. Released Date Page No.	IE-SP-018 2011/02/20 3/15
5 Str 3 7	vucture Graph		4		5	
		1 Ceramic s 2 Bottom inne 3 Top inner 4 Resistiv 5 Protective	e layer 9	Marking Terminal inner electro Ni plating Sn plating	de	
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6 Reliability Test

6.1 Electrical Performance Test

ITEM		Conditions	Specifications			
	_1VI			Resistors		
Tempe Coeffic Resis	ient of	TCR (ppm/°C) = $\frac{(R2-R1)}{R1(T2-T1)} \times 10^{6}$ R1: Resistance at room temperature R2: Resistance at -55°C or +125°C T1: Room temperature T2: Temperature -55°C or +125°C Refer to JIS-C5201-1 4.8	Refer to item 3.	general specifications		
Short	Time	Applied 2.5 times rated voltage for 5 seconds and	$\pm (0.5\% + 0.05)$	Ω)		
Over		general specifications) Refer to JIS-C5201-1 4.13		mechanical damage.		
Insula Resis	tance	Put the resistor in the fixture, add 100 VDC in + ,- terminal for 60 sec then measured the insulation resistance between electrodes and insulating enclosure or between electrodes and base material. Refer to JIS-C5201-1 4.6 Metal block measuring Point A Base material Insulating enclosure surface R0.5mm	≧ 10 ⁰Ω			
Diele Withs Volt	stand	Put the resistor in the fixture, add VAC (see SPEC below) in +,- terminal for. RTX02 \ 03 apply 300 VAC 1 minute. RTX05 \ 06 \ 12 \ 20 \ 25 apply 500 VAC 1 minute. Refer to JIS-C5201-1 4.7	No short or burn	ed on the appearance.		
Interm Over		Put the tested resistor in chamber under temperature $25\pm 2^{\circ}$ C and load the rated DC voltage for 1 sec on , 25 sec off , 10000^{+400}_{-0} test cycles, then it be left at no-load for 1 hour ,then measure its resistance variance rate. Refer to JIS-C5201-1 4.13	± (0.5%+0.05	Ω)		
Noise	Level	Refer to JIS-C5201-1 4.12	Resistan R <100	$\begin{array}{llllllllllllllllllllllllllllllllllll$		
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6.2 Mechanical Performance Test

ITE	М		Conditions	Specifications
				Resistors
Core E Stren	ngth	1.02 Kgf } force on t 1.RTX02 、03 : prot 2.RTX05 、06 、12 、 Refer to JIS-C5201-	he sample for 10 sec. le R0.2 20 < 25 : probe R0.5 4.15	\pm (0.5%+0.05Ω) No evidence of mechanical damage. No side conductive peel off.
Term stren	igth	pushing force Test2:The resistor m force on the s termination is Refer to JIS-C5201-	1 4.16	Test1: No evidence of mechanical damage. Test2: ≧5N
solve	ent	20~25 $^{\circ}$ C for 5 \pm 0.5 r room for 48 hr, and r rate. Refer to JIS-C5201-	e immersed into isopropyl alcohol of nin, then the resistor is left in the neasured its resistance variance 1 4.29	No evidence of mechanical damage, no G2 overcoating and Sn layer by leaching.
Soldera		temperature of 105°(pressure of 1.22× 10 after left the tested re hours or more. Test method: Test item1 (solder The resistor be im temperature 235± is left as placed ur solder area. Test item2 (wetting Add flux into resist balance machine, must be measured Testing conditions for Solder temperature Immersion speed Immersion depth Immersion angle Mass of solder ball	5 Pa for a duration of 4 hours. Then esistor in room temperature for 2 pot test): mersed into solder pot in 3 °C for 2± 0.5 sec, then the resistor oder microscope to observed its g balance method): ors, then put resistor into wetting refer to condition as below, then I and recorded its time changed. wetting balance method with solder pot Condition 235± 3°C 1 to 5 mm/s 0.10 mm Horizontal 25mg →0402 \ 0603 200mg →0805 \ 1206 \ 1210 \ 2010 \ 2512	1.Test item 1: Solder coverage over 95% 2.Test item 2: Zero cross time within 3 seconds.
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Specifications ITEM Conditions Resistors Resistance to The tested resistor be immersed into molten solder of $(0.5\% + 0.05\Omega)$ soldering heat $260\pm 5^{\circ}$ for 10 seconds. Then the resistor is left in the No evidence of electrode damage. room for 1 hour. No side conductive peel off. Refer to JIS-C5201-1 4.18 Solder tested resistor on to PC board. add force in the Bending \pm (0.5%+0.05 Ω) Test middle down, and under load measured its resistance No evidence of mechanical damage. variance rate. No terminal peel off and core body D: RTX02 、03 、05=5mm cracked. RTX06 \ 12=3mm RTX20 \ 25=2mm Testing circuit board Resisto Solder Supporting jig 45 45 Chip resistor (Amount of bend R OHM Meter Refer to JIS-C5201-1 4.33 Leaching Test The tested resistor be immersed into molten solder of 1.Solder coverage over 95%. 260+ 5°C for 30 seconds. Then the resistor is left as 2. The underlying material (such as placed under microscope to observed its solder area. ceramic) shall not be visible at the crest corner area of the electrode. The resistor shall be mounted by its terminal leads to Vibration $\pm (0.5\% + 0.05\Omega)$ the supporting terminals on the solid table. The entire No evidence of mechanical damage. frequency range : from 10 Hz to 55 Hz and return to 10 Hz, shall be transferred in 1 min. Amplitude :1.5 mm This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (a total of 6 hr) Refer to JIS-C5201-1 4.22

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5.3 Environmental Test

ITEM	Conditions		Specifications			
	Conditions		Resistors			
Resistance to	Put tested resistor in chamber under tem		± (0.5%+0.05Ω)			
Dry Heat	1000 +48/-0 hours. Then leaving the tes temperature for 60 minutes , and measu variance rate.	No evidence of mechanical damage.				
	Refer to JIS-C5201-1 4.25					
Thermal Shock	Put the tested resistor in the therma under the temperature cycle which s following table shall be repeated 300 consecutively. Then leaving the test room temperature for 1 hours, and r resistance variance rate.	\pm (0.5% + 0.05 Ω) No evidence of mechanical damage.				
	T	esting Condition				
	Lowest Temperature	-55± 5℃				
	Highest Temperature	125 ± 5℃				
		15 minutes each				
Localizer Life	Refer to MIL-STD 202 Method 107					
Loading Life in Moisture	Put the tested resistor in the chamber un 2°C, relative humidity 90~95% and load minutes on, 30 minutes off, total 1000 he tested resistor in room temperature for 6 measure its resistance variance rate. Refer to JIS-C5201-1 4.24	\pm (0.5%+0.05 Ω) No evidence of mechanical damage.				
Load Life	Put the tested resistor in chamber u	nder temperature	$\pm (0.5\% + 0.05\Omega)$			
		for 90 minutes on, 3 leaving the tested minutes, and	¹ No evidence of mechanical damage.			
Low	Put the tested resistor in the chambe		$\pm (0.5\% + 0.05\Omega)$			
Temperature Operation	temperature 25° C. Decreasing the term and keep the temperature at -55° C the rated voltage for 45 minutes on, Then leaving the tested resistor in ro 8± 1 hours, and measure its resista Refer to MIL-R-55342D 4.7.4					
Whisker Test			Max. 50 μ m			
	Minimum storage temperature	-40± 2℃				
	Maximum storage temperature	e 85± 2°C				
	Temperature-rataining time	7 min.				
	Number of temperature cycles 1,500					
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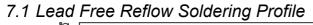
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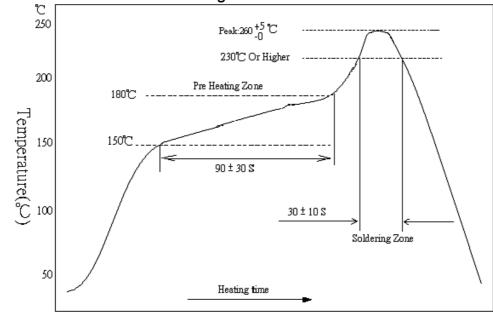
Thin Film Chip Resistors Product Specification

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	Conditions	Specifications				
ITEM	Conditions	Resistors				
	◎Test item 2 (Constant temperature/humidity test):					
	Temperature 85℃					
	Humidity 85%					
	Testing duration 500± 4 hours					
	 Inspection: Inspect for whisker formation on specimens that underwent the acceleration test specified in subciause 4.2, with a magnifier (stereo microscope) of about 40 or higher magnification. If judgment is hard in this method, use a scanning electron microscope (SEM) of about 1,000 or higher magnification. 					

7 Recommend Soldering Method





7.2 Soldering Iron: temperature 350 $\mathcal{C}\pm$ 10 \mathcal{C} , dwell time shall be less than 3 sec.

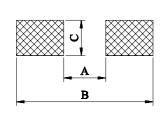
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8 Recommend Land Pattern Design (For Reflow Soldering) : (mm)



DIM TYPE	А	В	С
RTX02	0.5	1.5	0.6
RTX03	0.8	2.1	0.9
RTX05	1.2	3.0	1.3
RTX06	2.2	4.2	1.6
RTX12	2.2	4.2	2.8
RTX20	3.5	6.1	2.8
RTX25	3.8	8.0	3.5

9 Marking Diagrams:

- 9.1 RTX05、06、12、20、25 ± 0.1%、± 0.25%、± 0.5%、± 1% Tolerance:
- 9.1.1.1 Resistance Range \geq 100 Ω : 4 digits in E-24 series or E-96 series, first three digits are significant figures, forth digit is multiplier (10[×]).

 $1002 = 100 \times 10^2 = 10000 \Omega = 10 K \Omega$

9.1.1.2 Resistance Range < 100 Ω : 4 digits in E-24 series or E-96 series, three digits are significant figures, R digit is multiplier (10[×]).

 $\langle EX \rangle$ Marking \rightarrow 10R2 , R digit is multiplier (10⁻¹).

 $10R2 = 102 \times 10^{-1} = 10.2 \Omega$

Marking \rightarrow 1R02 ,R digit is multiplier (10⁻²).

 $1R02 = 102 \times 10^{-2} = 1.02 \Omega$

9.2 *RTX03* ± 0.1% 、 ± 0.25% 、 ± 0.5% 、 ± 1% Tolerance: For EIAJ-96 Marking.

《EX》Marking→47B

 $47B = 301 \times 10^{1} = 3010 \Omega = 3.01 K \Omega$

If the resistance is not in E-96 series and in E-24 series ,the marking is expressed by E-24 series and one short bar under marking letter.

R value > 100 Ω :marking 39<u>1</u> 39<u>1</u>=39 x10¹=390 Ω

R value $< 100 \Omega$:marking 390 390=39 x10°=39 Ω

9.3 RTX02 No Marking

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9.4 EIAJ-96 Marking:

This table shows the first two digits for the three-digits EIAJ-96 part marking scheme. The third character is a letter multiplier:

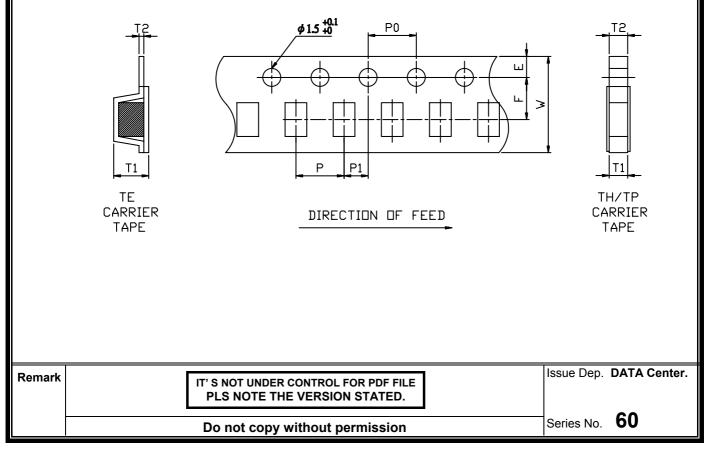
Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω
01	100	13	133	25	178	37	237	49	316	61	422	73	562	85	750
02	102	14	137	26	182	38	243	50	324	62	432	74	576	86	768
03	105	15	140	27	187	39	249	51	332	63	442	75	590	87	787
04	107	16	143	28	191	40	255	52	340	64	453	76	604	88	806
05	110	17	147	29	196	41	261	53	348	65	464	77	619	89	825
06	113	18	150	30	200	42	267	54	357	66	475	78	634	90	845
07	115	19	154	31	205	43	274	55	365	67	487	79	649	91	866
08	118	20	158	32	210	44	280	56	374	68	499	80	665	92	887
09	121	21	162	33	215	45	287	57	383	69	511	81	681	93	909
10	124	22	165	34	221	46	294	58	392	70	523	82	698	94	931
11	127	23	169	35	226	47	301	59	402	71	536	83	715	95	953
12	130	24	174	36	232	48	309	60	412	72	549	84	732	96	976
	Y = 1	0 ⁻² X =	= 10 ⁻¹	A=10)⁰ B	=10 ¹	C = 1	0 ² D=	=10 ³	E=10	$)^4 F =$	= 10 ⁵			

10 Plating Thickness:

10.1Ni: ≧1 µ m 10.2Sn(Tin): ≧3 µ m 10.3Sn(Tin): Matte Sn

11 Taping Specifications:

11.1Tape Dimension



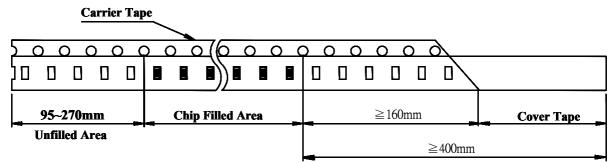
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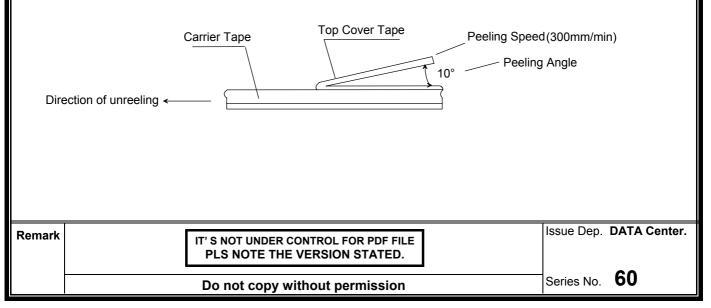
Unit: mm DIM В W Ε F Τ1 **T2** Ρ **P0** 10x P0 **P1** Packaging Α TYPE TH 8.0± 0.2 1.75± 0.1 3.5± 0.05 0.45+0.2/-0 0.45± 0.05 2.0± 0.1 4.0± 0.05 Carrier **RTX02** 1.15[±] 0.05 0.65[±] 0.05 40.0± 0.2 2.0± 0.05 Tape 4.0± 0.1 **RTX03** 1.80± 0.1 1.00± 0.1 8.0± 0.2 1.75± 0.1 3.5± 0.05 0.60+0.2/-0 0.60± 0.1 4.0± 0.05 40.0± 0.20 2.0± 0.05 TP RTX05 2.40± 0.10 1.65± 0.10 8.0± 0.20 1.75± 0.10 3.5± 0.05 0.75+0.2/-0 0.75± 0.10 4.0± 0.10 4.0± 0.05 40.0± 0.20 2.0± 0.05 Carrier 40.0± 0.20 RTX06 2.30± 0.1 0.75+0.2/-0 0.75± 0.1 4.0± 0.1 2.0± 0.05 Tape 1.55 ± 0.1 8.0+ 0.2 1.75 ± 0.1 3.5 ± 0.05 4.0 ± 0.05 **RTX12** 3.50± 0.2 0.75+0.2/-0 0.75± 0.1 4.0± 0.1 40.0± 0.20 2.0± 0.05 1.90± 0.2 8.0± 0.2 1.75± 0.1 3.5± 0.05 4.0± 0.05 ΤE 5.50± 0.2 RTX20 2.80± 0.2 5.5± 0.05 0.85± 0.15 0.23± 0.15 4.0± 0.1 4.0± 0.05 40.0± 0.20 2.0± 0.05 12.0± 0.2 1.75± 0.1 Carrier RTX25 6.70± 0.2 3.40± 0.2 12.0± 0.2 1.75± 0.1 5.5± 0.05 0.85± 0.15 0.23± 0.15 4.0± 0.1 4.0± 0.05 40.0± 0.20 2.0± 0.05 Tape

11.2Lead Dimensions:



11.3Cover Tape Peel off Strength

Specifications: 0402 => 0.07~0.5N (7.1~51gf) 0603 \cdot 0805 \cdot 1210 \cdot 2010 \cdot 2512=> 0.07~0.7N (7.1~71.4gf)



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11.4Packaging QTY:

		Packaging QTY (pcs/reel)															
TYPE	Таре		Paper								Plastic						
	Width	2 mm Pitch			4 mm Pitch				4 mm Pitch								
		TH	H2	H3	H4	TP	P2	P3	P4	TE	E2	E3	E4				
RTX02	8 mm	10,000	20,000	30,000	40,000												
RTX03	8 mm																
RTX05	8 mm					5,000	10,000	15,000	20,000								
RTX06	8 mm]	1m	8 mm	8 mm				5,000	10,000	13,000	20,000				
RTX12	8 mm																
RTX20	12 mm							-	-	4,000	8,000	12,000	16,000				
RTX25	12 mm									- ,000	0,000	12,000	10,000				
Reel	Туре	7"	10"	13"	13"	7"	10"	13"	13"	7"	10"	13"	13"				

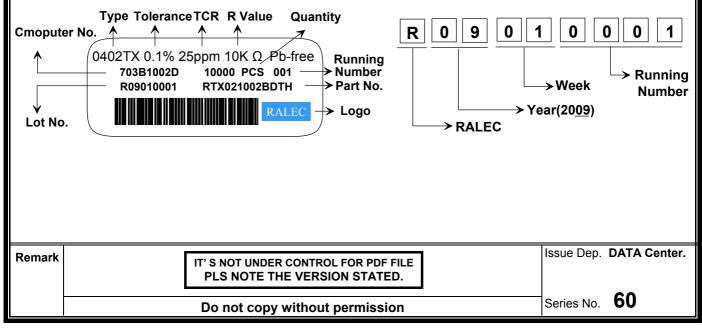
11.4.1Typical taping type: TH 、TP 、TE

11.4.20ther taping type are upon customer's request.

11.5Reel Dimensions:

eel Dimensions:						Un	it:mm
	Reel Type/ Tape	Wa	м	Α	В	С	D
	7" reel for 8 mm tape	9.0 ± 0.5	178 ± 2.0				60.0 ± 1.0
	7" reel for 12 mm tape	13.8 ± 0.5	178 ± 2.0	± 0.5 ±	13.5	21.0 ± 0.5	80.0 ± 1.0
	10" reel for 8 mm tape	10.0 ± 0.5	254 ± 2.0		± 0.5		100.0 ± 1.0
	13" reel for 8 mm tape	10.0 ± 0.5	330 ± 2.0				100.0 ± 1.0

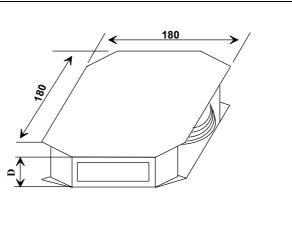
11.6Label:



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11.7 Inner Box

Reel Number	D Dimension (mm)	
1	12	
2	24	
3	36	
4	48	
5	60	
6	72	
7	84	
8	96	
9	108	
10	120	



11.8 Box

10R Inner Box Number	L(mm)	W(mm)	D(mm)	
2	272	205	210	
4	375	280	210	RALEC
8	544	380	210	

11.9Box (For China)

10R Inner Box Number	L(mm)	W(mm)	D(mm)	
2	272	205	210	
4	375	280	210	RALEC C
8	544	380	210	

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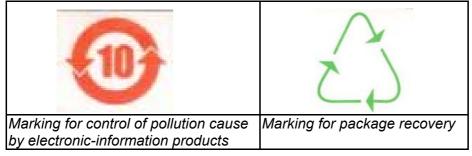
12 Measurement Point

背面電極量測			Unit : mm
A	DIM TYPE	Α	В
	RTX02	0.80 ± 0.05	0.24 ± 0.05
	RTX03	1.35± 0.05	0.35 ± 0.05
	RTX05	1.80± 0.05	0.34 ± 0.05
	RTX06	2.90± 0.05	0.35 ± 0.05
• Current Terminal	RTX12	2.90 ± 0.05	0.35 ± 0.05
Voltage Terminal	RTX20	4.50 ± 0.05	1.15 ± 0.05
	RTX25	5.90 ± 0.05	1.60 ± 0.05

13 Stock period

13.1The temperature condition must be controlled at $25 \pm 5 C$, the R.H. must be controlled at $60 \pm 15\%$. The stock can maintain quality level in two years.

14 The carton packaged for electronic-information products is made by the symbol as follows: (For china)



- 15 For this part. It does not use the materials that include the substances specified in RoHS [,] the detail refer to the part of prohibition or exclusion items in RoHS (2002/95/EC).
 - 1. Cadmium and cadmium compounds (permissive content <100 ppm)
 - 2. Lead and lead compounds (*permissive content* <1000 ppm) Exceptions specified:
 - (1). Lead contained in the glass of cathode ray tubes, electronic components and fluorescent tubes.
 - (2). The glass material used in the electronic components, which includes resistor elements, conductive pastes (silver or copper ones), adhesives, glass frit and sealing materials.

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Specification	-

(3). Mercury and its mercury compounds (permissive content <100 ppm)

(4). Hexavalent chromium compounds (permissive content <100 ppm)

(5). Polybrominated biphenyls (PBB) (permissive content <100 ppm)

(6). Polybrominated diphenylethers (PBDE) (permissive content <100 ppm)

16 Attachments

16.1Document Revise Record Paper

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